

Coilmaster



SPECIFICATION APPROVAL

CUSTOMER	:	Ozdisan
PRODUCT	:	SDR75H-102K-LF
		Pb-free
CODE NO.	:	C00575133
CUS. CODE	:	
SPEC.NO.	:	C-0575-133(01)
DATE	:	22-Aug-22
CU	JS	TOMER APPROVAL

Coilmaster Electronics Co., Ltd.

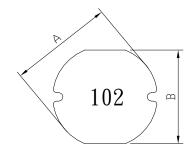
3F ,NO.211 HUAN BEI ROAD, CHUNG-LI DISTRICT TAOYUAN CITY, TAIWAN.

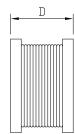
TEL: (886)34228279 FAX: (886)34525688

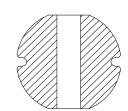
PREPARED BY	APPROVED BY	AUTHORIZED BY	
JEAN	TONY	MASCOT	

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22
SPEC.NO.	C-0575-133(01)	SPECIFICATION	CODE NO.	C00575133

EXTERNAL DIMENSIONS:







ELECTRICAL CHARACTERISTIC:

 $L(\mu H)$: 1000±10% 100KHz 0.25V

 $DCR(\Omega)$: 4.50 Max.

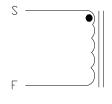
 $Isat(A): \hspace{1.5cm} 0.34 \hspace{1.5cm} Max. \hspace{1mm} (\hspace{1mm} 0.34 \hspace{1.5cm} A \hspace{1mm} MAX \geq \hspace{1mm} 0 Ax 90\% \hspace{1mm})$

INDUCTANCE DROP: 10% Typ. @ IDC 0.34 A

Irms(A): 0.21 Max. Operating Temperature Range : $-40^{\circ}\text{C} \sim + 125^{\circ}\text{C}$

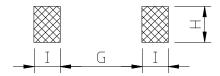
SCHEMATIC DRAWING:

PCB PATTERN:



START FOR STAND

 ϕ 0.12x172.5Ts(Ref.)



G: 2.0 m/m H: 7.5 m/m

I: 3.0 m/m

MATERIAL LIST :

NO	ITEM	MATERIAL	SUPPLIER OF THE MATERIAL
1	CORE	CT0705CS B3.0	
2	WIRE	Φ0.12 2SFFW(180°C)	
3	INKING	V0001-684	
4	SOLDER	SNCU3.0	

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22
SPEC.NO.	C-0575-133(01)	SPECIFICATION	CODE NO.	C00575133

TEST DATA

	ELECTRICAL CHARACTERISTICS							
MEAS. ITEM	L(µH)	DCR(Ω)	Isat(A)					
TEST FREQ.	100KHz 0.25V	Max.	Max.					
YOUR			L(0.34A)					
SPEC.	1000±10%	4.50	≥0Ax90%					
1	991.00	2.930	Ok					
2	938.00	2.940	Ok					
3	948.00	2.930	Ok					
4	948.00	2.920	Ok					
5	937.00	2.860	Ok					
6	938.00	2.990	Ok					
7	933.00	2.890	Ok					
8	949.00	2.880	Ok					
9	932.00	2.910	Ok					
10	939.00	2.950	Ok					
Х	945.300	2.920						
R	59.00	0.13						

	DIMENSION							
MEAS. ITEM	А	В	С	D				
TEST FREQ.	m/m	m/m	m/m	m/m				
YOUR								
SPEC.	7.8±0.3	7.0±0.3		5.0±0.5				
1								
2								
3								
4								
5								
6								
7								
8								
9								
10								
Х	#DIV/0!	#DIV/0!		#DIV/0!				
R	0.00	0.00		0.00				

		I-102K-LF COIL			DATE	2022/8/22
		5-133(01)	SPECIFICA	TION	CODE NO	O. C00575133
TEST IT	EMS	SPI	ECIFICATIONS	TEST	CONDITION	S / TEST METHODS
ELECTRICAL PARTICULAR		REFER TO S CHARACTE 40°C MAX (A	STANDARD ELEC-TRICAL RISTIC LIST.	APPLIED TH CHANGE SH VALUE AND MORE THAN 1. APPLIED T 2. TEMPERA THERMON APPLIED 1.5	EQUIV E CURRENT TO OULD BE LESS TEMPERATUR 140°C THE ALLOWED TURE MEASUR METER. TIMES OF RAT	D COILS THE IDUCTANCE THAN 10% TO INITIAL RE RISE SHOULD NOT BE DC CURRENT FOR 4 HOURS RE BY DIGTAL SURFACE FED ALLOWED DC CURRENT LIOD OF 5 MINUTES.
MECHANICAL I	PERFORM	ANCE TEST	<u>T</u>	PREHEAT:15	0°C 60SECS	
SOLDER HEAT RESISTANCE VIBRATION TEST (LOW FREQUENCY)		1. INDUCTORS SHOULD HAVE NO EVIDENCE OF ELEC- TRICAL AND MICHANICAL DAMAGE 2. INDUCTANCE SHOULD NOT HANGE MORE THAN±10% 3. SOLDER MATERIAL WILL BE LEAD FREE.		SOLDER TEN 255±5°C FLUX: ROXI DIP TIME:10		Preheating Dipping Natural cooling 60
				1.AMPLITUDE: 1.5 mm 2.FREQUENCY: 10-55-10HZ / 1 MIN 3.DIRECTION: X, Y, Z 4.DURATION: 2 HRS/X, Y, Z		
				INDUCTORS HEIGHT OF 1		ROPPED 10 TIMES FROM A

PRODUCT	SD	R75H-102K-LF		COIL	DATE	2022/8/22
SPEC.NO.	C-	0575-133(01)	SPEC	CIFICATION	CODE NO.	C00575133
TEST ITEM	IS	SPECIFICA	TIONS	TEST CON	DITIONS / TEST	METHODS
MECHANICAL I	PERF	ORMANCE TEST	<u>r</u>			
SOLDERABILITY 1	ΓEST	MORE THAN 90% TERMINAL ELECT SHOULD BE COVE SOLDER.	RODE	AFTER FLUXING, INDUC BE DIPPEDIN A MELTED BATH AT 255±5°C FOR 5	SOLDER	Preheating Dipping Natural cooling 60
COMPONENT ADHESION (PUSH TEST)		1.5Kg Min		THE DEVICE SHOULD B SOLDERED (255±5°C FOI SECONDS) TO A TINNED SUBSTRATE. A DYNOME GAUGE SHOULD BE APP THE SIDE OF THE COMPODEVICE MUST WITH- ST. MINIMUM FORCE OF 1.5 WITHOUT AILURE OF TETERMINATION . ATTACH COMPONENT.	R 10 O COPPER TER FORCE LIED TO ONENT. THE AND A Kg IE	ASS EPDAY SUBSTRATE TH COPPER CLAD
COMPONENT ADHESION (PULL TEST)		1.5Kg Min		1.INSERT 10cm WIRE INT REMAINING OPEN EYE I ENDS OF EVEN WIRE LE UPWARD AND WIND TOO 2. TERMINAL SHALL NO BEREMARKABLY DAMA	BEND THE NGTHS GETHER I	
FLEXTURE STREN	GTH	THE FORCES APPI SHOULD NOT DAN DIELECTRIC.		SOLDER A CHIP ON A TE SUBSTRATE, BEND THE BY 2mm AND RETURN.		Bending 45mm 45mm 40mm
RESISTANCE TO SOLVENT TEST		THERE SHOULD B CASEDEFORMATI CHANGE IN APPE BITERATION OF M	ON, ARANCE OR	INDUCTERS SHALL WITI	HSTAND 6 MINTES	OF ALCOHOL

PRODUCT	SDR75H-102K-LF	OR75H-102K-LF C		DATE	2022/8/22		
SPEC.NO.	C-0575-133(01)	SPECIF	ICATION	CODE NO.	C00575133		
TEST ITEM	S SPECI	FICATIONS	TEST CO	ONDITIONS / TES	ST METHODS		
CLIMATIC TEST	<u>r</u>						
TEMPERATURE CHARACTERISTIC			- 40°C ∼+125°C				
HUMIDITY TEST			60°C±2°C / 96±2 HO	URS			
LOW TEMPERATUR STORAGE	1.APPEARANCI 2.INDUCTANCI	1.APPEARANCE:NO DAMAGE 2.INDUCTANCE:WITHIN±10% OF INITIAL VALUE.		1.TEMPERATURE:- 25° C $\pm 2^{\circ}$ C 2.TIME: 96 ± 2 HOURS			
THERMAL SHOCK TEST	INITIAL VALUI			125±5°C FOR 30 MINUTES. +80±5°C FOR 30 MINUTES. 2.TOTAL: 10 CYCLES 125±5°C FOR 30 MINUTES. Room temperature 30 min 30 min 30 min 25°C			
HIGH TEMPERATU STORAGE	RE			1.APPLIED CURRENT: MAX RATED CURRENT 2.TEMPERATURE:80℃±2℃			
NOTE: INDUCTOR	S ARE TO BE TESTED	AFTER 2 HOUR AT	 ROOM TEMPERATUR	Е.			
LIFE TEST							
HIGH TEMPERATU LOAD LIFE TEST	INDUCTORS SE	INDUCTORS SHOULD BE NO EVIDENCE OF SHORT OR OPEN CIRCUIT		1. TEMPERATURE: $80\pm2^{\circ}$ C 2. TIME: 500 ± 12 HOURS 3. LOAD: ALLOWED DC CURREN			
HUMIDITY LOAD I TEST	CIRCUIT			1. TEMPERATURE: 60±2℃ 2. R.H.: 90-95% 3. TIME: 500±12 HOURS 4. LOAD: ALLOWED DC CURREN			

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22
SPEC.NO.	C-0575-133(01)	SPECIFICATION	CODE NO.	C00575133

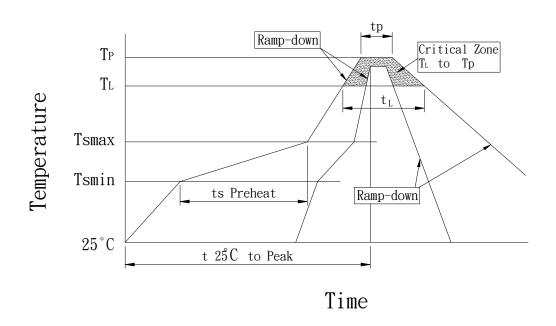
RECOMMENDED SOLDERING CONDITIONS:

CLASSIFICATION REFLOW PROFILES

Profile Feature	Sn-Pb Euteo	tic Assembly	Pb-Free Assembly		
Profile Feature	Large Body Small Body		Large Body Small B		
Average ramp-up rate (T _L to T _P)	3℃/seco	ond max.	3°C/seco	ond max.	
Preheat -Temperature Min (Ts _{min}) -Temperature Min (Ts _{max}) -Time (min to max) (ts)	100°C 150°C 60-120 seconds		150°C 200°C 60-180 seconds		
Tsmax to T _L -Ramp-up Rate			3°⊜/seco	ond max.	
Time maintained above: -Temperature (T _L) -Time (t _L)		183°C 60-150 seconds		7℃ seconds	
Peak Temperature (Tp)	225 +0/-5℃	240 +0/-5℃	245 +0/-5℃	255 +5/-5℃	
Time within 5℃ of actual Peak Temperature (tp)	10-30 seconds	10-30 seconds	10-30 seconds	20-40 seconds	
Ramp-down Rate	6℃/seco	6℃/second max.		ond max.	
Time 25℃ to Peak Temperature	6 minut	6 minutes max.		es max.	

Note: All temperatures refer t topside of the package. Measured on the package body surface.

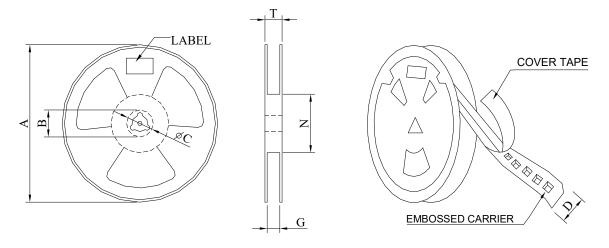
REFLOW SLODERINGS



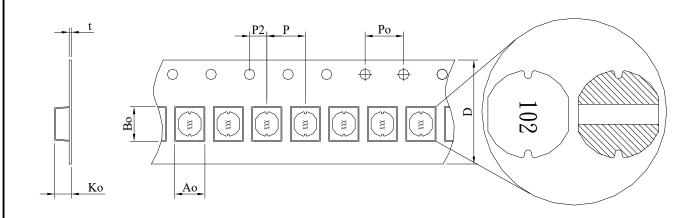
COILMASTER ELECTRONICS CO., LTD.

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22
SPEC.NO.	C-0575-133(01)	SPECIFICATION	CODE NO.	C00575133

PACKAGE:



*CARRIER TAPE WIDTH: D



STYLE	DIMENSIONS (m/m)															
	SITLE	Q'TY (PCS)	Α	В	С	D	G	N	Т	Ao	Во	Ko	t	Р	Ро	P2
	330	1000	330	21 ±0.8	13 ±0.5	16	18+0	50-0	22.4	_	_		_	12	4	_

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22	
SPEC.NO. C-0575-133(01)		SPECIFICATION	CODE NO.	C00575133	
LABLE :	CODE NO. ←	70mm	40mm		
CODE N	CO025005 Custo ITEM QTY: N.W: G.W: Coilm	omer: P/N: XXXXXXXX-LF XXX PCS KG KG	Pb	100mm	
				<i>)</i>	

COILMASTER ELECTRONICS CO., LTD.

PRODUCT	SDR75H-102K-LF	COIL	DATE	2022/8/22
SPEC.NO.	C-0575-133(01)	SPECIFICATION	CODE NO.	C00575133

Cautions and Warnings:

- 1. All of the components are manufactured, designed, and promoted for applying in general electronics devices, for the specific area such as automotive, medical, military and aerospace except for general electronic devices, Coilmaster must be asked for written approval before incorporating the components into these areas.
- 2. The components that will be used in high-reliability / high level of safety applications should be pre-evaluated by the end customer.
 Especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health.
 The customer shall be responsible for evaluating and confirming Coilmaster product is suitable for use in customer's applications.
- 3. Customer must be cautioned to verify that data sheets are the updated ones before placing orders. In the individual cases, any trouble or failure of electronic components happens during their long span cannot be eliminated even follow the instruction with existing technology.
- 4. Washing / Cleaning process may jeopardize the product and cause the defect. Washing agents may harm the long-term functionality of the product
- 5. The storage period should not be longer than 12 months (In the specific storage environment). The oxidization may happen on the terminals.
 Hence all the products shall be used within 12 months after the shipping date. If the time is over 12 months, please check the solderability before use it.
- 6. Products should not be kept in unsuitable storage conditions, such as areas susceptible to high humidity, high temperatures, dust or corrosion.
- 7. Don't touch electrodes directly with bare hands as oil secretions may inhibit soldering. Always ensure optimum conditions for soldering.
- 8. Don't bend the terminals or subject them to excessive stress.
- 9. Please ensure that all terminals and case lugs are completely fixed with solder onto PCB
- 10. Ensure the tuning slug or cap is not fixed by solder flux during the production process.
- 11. Avoid placing coils near the edge of the PCB
- 12. Don't touch any exposed winding part and avoid coming into contact with the guide of the electrode in automatic mounting
- 13. The inductor / coil / common mode choke generates heat when current is applied. Please take care of this during the design.
- Always handle the product with care to prevent the damage.
- 15. Our specification specifies the quality of the component as a single unit. Please ensure the component is thoroughly evaluated in your application circuit.

 Even for customized products, conclusive validation of the component in the circuit can only be carried out by customer.
- 16. The general testing condition is in the room temperature 25 +/- 5°C and humidity under 65% RH, which is applied to all products.
- 17. If have any query, please feel free to contact our sales department.